



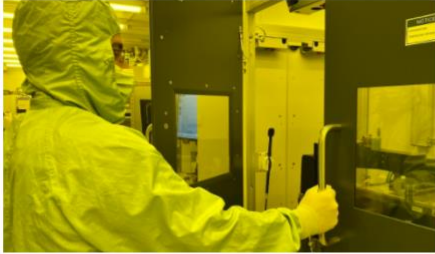
EV GROUP Brings High-speed High-precision Metrology to 3D Heterogeneous Integration – November 19, 2021



Electronics Packaging – From Afterthought to Product Differentiation

Traditional electronics packaging is everything with wire or ribbon bond interconnects on a ceramic, metal lead frame, or organic laminated substrates, and it is typically a single die package. Advanced packaging starts with flip-chip interconnects (bumps, micro-bumps, Cu-pillars), mainly on organic laminated substrates, and has been transitioning during the last decade into wafer-level packaging (WLP).

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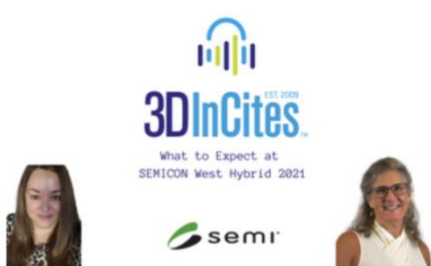
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Member of the Week



Based in San Jose, California, SVXR was founded in 2013 expressly to bring high speed inspection and metrology technology to the semiconductor packaging industry. SVXR's founders anticipated the need to deploy inline 100% transmissive inspection into the semiconductor packaging manufacturing process and developed the company's technology with this end in mind. The results, SVXR's HR-AXI technology suite brings together the company's unique data acquisition architecture with proprietary machine learning analysis techniques to provide customers with process monitoring and defect detection capabilities unique to the market. HR-AXI is not traditional X-ray imaging. Its data collection architecture rapidly collects large field of view transmissive data at full resolution with 16 bit high bandwidth sensitivity.

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Company News

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Events

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[IEEE EPTC 2021](#)

Dec 1, 2021

Bonding Solutions for Next-Generation Advanced Packaging (Webinar)

[December 2, 2021, 9am PT](#)

[December 3, 2021, 9am China Standard](#)

[SEMICON West 2021](#)

December 7-9

[2021 IEEE International Electron Devices Meeting](#)

December 12-15



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